



NTC thermistors for temperature measurement

Ring NTC

Series/Type:	K2150/700/3%
Ordering code:	B57150K2701H
Date:	2011-03-22
Version:	2

Application

- Temperature measurement

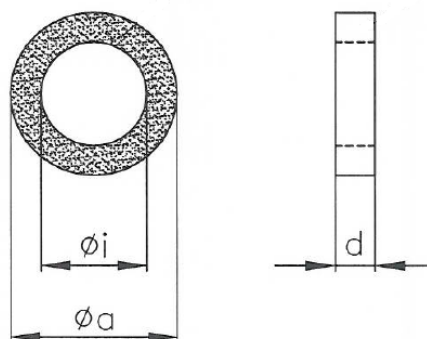
Version

NTC ring with silver termination
Ring-geometry:

$$\varnothing a = 5,2 \pm 0,3 \text{ mm}$$

$$\varnothing i = 3,2 + 0,3$$

$$d = 1,0 \pm 0,3 \text{ mm}$$



 Metallization

Free zone of metallization 0 – 0,2mm allowed

Ratings and characteristics

Climatic category (IEC 60068-1)

: **55/155/21**

Lower category temperature

[°C] : **-55**

Upper category temperature

[°C] : **155**

Rated resistance R_N // Tolerance

R_N [Ω // %] : **83,00 // ± 3%**

Rated temperature

T_N [°C] : **80**

B-value : $B_{(25/100)}$ // Tolerance
R/T-Curve no. // R_{25}

B_N [K//%] : **4100 // ± 1**
[n//Ω] : **1026 // 700,1**

Max. power rating at 25°C

P_{25} [mW] : **150**

Dissipation factor (in air)

δ_{th} [mW/K] : **Approx. 3,0**

Thermal cooling time constant (in air)

τ_C [s] : **Approx. 15**

Heat capacity

C_{th} [mJ/K] : **Approx. 45**

NTC Resistance Temperature Curve

R/T-Curve 1026 / A01 B(25/100) 4100[K] ± 1 [%]
R at 25°C 700,1 [Ohm] Rn at 80°C 83,00 [Ohm] ± 3 [%]

Temp. [°C]	R Nom [Ω]	R Min [Ω]	R Max [Ω]	ΔR [±%]	ΔT [±°C]	α [%/K]
-55	73.973	66.402	81.544	10,2	1,4	7,5
-50	51.270	46.238	56.301	9,8	1,4	7,2
-45	35.965	32.581	39.350	9,4	1,3	7,0
-40	25.523	23.219	27.826	9,0	1,3	6,7
-35	18.314	16.728	19.899	8,7	1,3	6,5
-30	13.281	12.179	14.384	8,3	1,3	6,3
-25	9.730	8.956	10.505	8,0	1,3	6,1
-20	7.199	6.649	7.749	7,6	1,3	5,9
-15	5.376	4.983	5.770	7,3	1,3	5,7
-10	4.051	3.767	4.336	7,0	1,3	5,6
-5	3.080	2.872	3.287	6,7	1,2	5,4
0	2.361	2.208	2.513	6,5	1,2	5,2
5	1.824	1.711	1.937	6,2	1,2	5,1
10	1.420	1.336	1.504	5,9	1,2	4,9
15	1.114	1.051	1.177	5,7	1,2	4,8
20	880,1	832,4	927,9	5,4	1,2	4,6
25	700,1	663,8	736,4	5,2	1,2	4,5
30	560,6	532,7	588,4	5,0	1,1	4,4
35	451,7	430,3	473,1	4,7	1,1	4,3
40	366,2	349,6	382,8	4,5	1,1	4,1
45	298,6	285,7	311,6	4,3	1,1	4,0
50	244,9	234,8	255,0	4,1	1,1	3,9
55	202,0	194,0	209,9	3,9	1,0	3,8
60	167,4	161,1	173,7	3,7	1,0	3,7
65	139,5	134,5	144,5	3,6	1,0	3,6
70	116,8	112,8	120,7	3,4	1,0	3,5
75	98,23	95,07	101,4	3,2	0,9	3,4
80	83,00	80,51	85,49	3,0	0,9	3,3
85	70,44	68,18	72,70	3,2	1,0	3,2
90	60,03	58,01	62,06	3,4	1,1	3,2
95	51,37	49,56	53,18	3,5	1,1	3,1
100	44,14	42,52	45,76	3,7	1,2	3,0
105	38,06	36,61	39,52	3,8	1,3	2,9
110	32,95	31,64	34,25	4,0	1,4	2,9
115	28,62	27,44	29,79	4,1	1,5	2,8
120	24,94	23,89	26,00	4,2	1,6	2,7
125	21,81	20,86	22,76	4,4	1,6	2,6
130	19,14	18,28	19,99	4,5	1,7	2,6



Reliability Data

Testing acc. to AEC Q200 Rev D by type representatives

Test	Stand	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
High Temperature Exposure (Storage) 1	MIL-STD-202 Method 108	Storage at T = + 125°C t = 1000h	< 2%	no visible damage
High Temperature Exposure (Storage) 1	MIL-STD-202 Method 108	Storage at T = + 155°C t = 1000h	< 3%	no visible damage
Biased Humidity	MIL-STD-202 Method 103	85°C / 85% / 1000h 10% rated power	< 3 %	No visible damage
Operational Life	MIL-STD-202 Method 108	1000h / 150°C rated power - steady state	< 3 %	No visible damage
Thermal Shock	MIL-STD-202 Method 107	-55°C / 125°C / 1000cycl. < 20s change / 15min dwell / Air	< 3 %	No visible damage
Mechanical pressure test		70N / 10s / planar surface	< 1 %	No visible damage
Test at low temperature		-55°C / 1000h / unpow.	< 2 %	No visible damage

Cautions and warnings

Storage

- Store thermistors only in original packaging. Do not open the package before storage.
- Storage conditions in original packaging: storage temperature $-25^{\circ}\text{C} \dots +45^{\circ}\text{C}$, relative humidity $\leq 75\%$ annual mean, maximum 95%, dew precipitation is inadmissible.
- Do not store SMDs where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or SMDs may stick together, causing problems during mounting.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environments like corrosive gases (Sox, Cl etc.)
- After opening the factory seals, such as polyvinyl-sealed packages, use the SMDs as soon as possible.
- Solder thermistors after shipment from EPCOS within the time specified:
SMDs: 12 months
Leaded components: 24 months

Handling

- NTC thermistors must not be dropped. Chip-offs must not be caused during handling of NTCs.
- Components must not be touched with bare hands.
Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

Mounting

- When NTC thermistors are encapsulated with sealing material or overmolded with plastic material, the precautions given in chapter “Mounting instructions”, “Sealing, potting and overmolding” must be observed.
- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housing used for assembly with thermistor have to be clean before mounting.
- During operation, the thermistor’s surface temperature can be very high (ICL). Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling of the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand the temperature.
- Make sure that thermistors (ICLs) are adequately ventilated to avoid overheating.
- Avoid contamination of thermistor surface during processing.

Operation

- Use thermistors only within the specified operating temperature range.
- Use thermistors only within the specified voltage and current ranges (ICLs).
- Environmental conditions must not harm the thermistors. Use thermistors only in normal atmospheric conditions.
- Contact of NTC thermistors with any liquids and solvents should be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. Galden).
- Avoid dewing and condensation.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by malfunction (e.g. use VDR for limitation of overvoltage condition).

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.epcos.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.
6. Unless otherwise agreed in individual contracts, **all orders are subject to the current version of the “General Terms of Delivery for Products and Services in the Electrical Industry” published by the German Electrical and Electronics Industry Association (ZVEI)**.
7. The trade names EPCOS, BAOKE, Alu-X, CeraDiode, CSMP, CSSP, CTVS, DeltaCap, DigiSiMic, DSSP, FormFit, MiniBlue, MiniCell, MKK, MLSC, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SIP5D, SIP5K, ThermoFuse, WindCap are **trademarks registered or pending** in Europe and in other countries. Further information will be found on the Internet at www.epcos.com/trademarks.